FORM (Rev. P	08-29-200	R SHEET U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
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To the Honorable Commissioner o	10220538	
Name of conveying party(ies):		Name and address of receiving party(ies)
Takashi Hosaka	08-27-02	Name: Seiko Instruments Inc.
Additional name(s) of conveying party(ies) attached? ☐ Yes 🕱 No		Internal Address:
3. Nature of conveyance:		
	☐ Merger	Street Address: 8, Nakase 1-chome,
☐ Security Agreement	☐ Change of Name	Mihama-ku, Chiba-shi
☐ Other		City: Chiba State: Japan ZIP:
Execution Date: August 9, 2002		Additional name(s) & address(es) attached? ☐ Yes 🕱 No
4. Application number(s) or patent number	umber(s):	n, the execution date of the applications:
If this document is being filed tog	ether with a new applicatio	n, the execution date of the applications:
A. Patent Application No.(s)		n, the execution date of the application is:
09/639,709		SF = S
	Additional numbers a	B. Patent No.(s) CE SECTION ttached? © Yes & No
<u> </u>		1
Name and address of party to whom correspondence concerning document should be mailed:		6. Total number of applications and patents involved: 1
Name: Bruce L. Adams		7. Total fee (37 CFR 3.41)\$_40.00
Internal Address:		☑ Enclosed
monar rodross.		
		Authorized to be charged to deposit account any deficiency in enclosed fee
Street Address: Adams & Wilks		8. Deposit account number:
50 Broadway-31stFloor		01-0268
City: New York State:	NY ZIP: 10004	(Attach duplicate copy of this page if paying by deposit account)
72972002 DBYRME 00000011 09639709	DO NOT U	SE THIS SPACE
FC:581 40.00 0F	1	
 Statement and signature. To the best of my knowledge and the original document. 	d belief, the teregoing infor	mation is true prid correct and any attached copy is a true copy of
Bruce L. Adams	_ (\W.	August 19, 200 Date
Name of Person Signing	Total number of pages includin	Signature Date g cover sheet, attachments, and document:
		required cover sheet informat MAILING CERTIFICATE ON

ASSIGNMENT

WHEREAS, I, Takashi Hosaka, residing at c/o Seiko Instruments Inc., 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, Japan have invented new and useful improvements in <u>SEMICONDUCTOF</u> DEVICE HAVING BUMP WITH STRAIGHT COLUMN SEFVING AS LEAD AND METHOD OF MANUFACTUPING THEFECE

for which I have prepared an application for Letters Patent of the United States of America;

AND WHEREAS, Seiko Instruments Inc., located and doing business at 8, Nakase 1-chome, Mihama-ku, Chiba-shi, Chiba, Japan, is desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor;

NOW, THEREFORE, be it known by all whom it may concern, that for and in consideration of Ten Dollars (\$10.00) and other good and valuable consideration to me in hand paid, the receipt of which is hereby acknowledged, I have assigned, sold and transferred and by these presents do hereby assign, sell and transfer unto the said Seiko Instruments Inc. for the territory of the United States of America, my entire right, title and interest in and to the said invention, and in and to the said application, prepared and executed by me on NCVEMBFP 21, 2000, filed August 14, 2000 , Serial No.09/639,709 preparatory to obtaining Letters Patent thereon and in and to any and all divisions, reissues and continuations thereof, and in and to any Letters Patent that may be granted thereon; said invention, application and Letters Patent to be held and enjoyed by the said Seiko Instruments Inc., its legal representatives and assigns, as fully and entirely as the same would have been held by me had this assignment, sale and transfer not been made.

> PATENT REEL: 013224 FRAME: 0860

AND, I hereby covenant and agree that I will at any time upon the request and at the expense of said assignee execute and deliver any and all papers and do all lawful acts that may be necessary or desirable to perfect the title to said invention and to obtain Letters Patent therefor, and I hereby authorize and request the Honorable Commissioner of Patents and Trademarks to issue the said Letters Patent to the said Seiko Instruments Inc. in accordance with this assignment.

Executed this $\frac{9 \text{th}}{}$ day	of August , 2002 at
Witness:	·
Miwa Nakamura	Jahashi Hosaka (L.S.)
	(L.S.)
	(L.S.)
	(L.S.)
	(L.S.)
	(L.S.)
	(L.S.)

RECORDED: 08/27/2002

PATENT REEL: 013224 FRAME: 0861